

ID	R _{Ds} (ON)(Typ)	VDSS	
7A	1.1Ω	650V	

Applications:

- Switch Mode Power Supply(SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)

Features:

- Fast switching speed
- 100% avalanche tested
- Improved dv/dt capability

Ordering Information

Part Number	Package	Marking	Packing	Qty.
RS7N65F	T0-220F	RS7N65F	Tube	50 PCS

Absolute Maximun Ratings Tc= 25° C unless otherwise specified

Symbol	Parameter	RS7N65F	Units
VDSS	Drain-to-Source Voltage	650	V
ID	Continuous Drain Current TC=25 $^{\circ}$ C	7	Δ
IDM	Pulsed Drain Current (Note*1)	28	A
PD	Power Dissipation	35	W
VGS	Gate- to- Source Voltage	±30	V
EAS	Single Pulse Avalanche Engergy L = 10mH, VDD = 50V, RG = 25 Ω	165	mJ
	Maximum Temperature for Soldering		
TL TPKG	Leads at 0.063in(1.6mm)from Case for 10 seconds Package Body for 10 seconds	300 260	°C
TJ and TSTG	Operating Junction and Storage Temperature Range	-55 to 150	

* Drain Current Limited by Maximum Junction Temperature

Caution: Stresses greater than those listed in the" Absolute Maximum Ratings" Table may cause permanent damage to the device.



Thermal Resistance

Symbol	Parameter	RS7N65F	Units	Test Conditions
RθJC	Junction-to-Case	2.84	°C/W	Drain lead soldered to water cooled heatsink, PD adjusted for a peak junction temperature of + 1 5 0 $^\circ\!\!C$
RθJA	Junction-to- Ambient	40.25		1 cubic foot chamber,free air.

OFF Characteristics TJ= 25° C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
BVDSS	Drain- to- source Breakdown Voltage	650			V	VGS=0V,ID=250μ Α
IDSS	Drain- to- Source Leakage Current			1	μA	VDS=650V,VGS= 0V
	Gate- to- Source Forward Leakage			100	~ ^	VGS=30V ,VDS=0 V
IGSS	Gate- to- Source Reverse Leakage			-100	nA	VGS=-30V ,VDS= 0V

ON Characteristics TJ=25°C unless otherwise specified

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
RDS(on)	Static Drain- to- Source On- Resistance(Note*2)		1.1	1.35	Ω	VGS=10V,ID=3.5 A
VGS(TH)	Gate Threshold Voltage	3		4	V	VGS=VDS,ID=25 0μA

Resistive Switching Characteristics Essentially independent of operating temperature

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
td(ON)	Turn- on Delay Time		39		nS	VDS=325V ID=7A RG=25Ω
trise	Rise Time		23			
td(OFF)	Turn- OFF Delay Time		137			
tfall	Fall Time		60			



Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
Ciss	Input Capacitance		891			VGS=0V
Coss	Output Capacitance		87		pF	VDS=25V
Crss	Reverse Transfer Capacitance		10			f=1.0MHz
Qg	Total Gate Charge		32			VDS=520V
Qgs	Gate- to- Source Charge		4.6		nC	ID=7A VGS=10V
Qgd	Gate-to-Drain(" Miller") Charge		14			

Dynamic Characteristics Essentially independent of operating temperature

Source- Drain Diode Characteristics

Symbol	Parameter	Min.	Тур.	Max.	Units	Test Conditions
IS	Continuous Source Current			7	А	Integral pn- diode
ISM	Maximum Pulsed Current			28	А	in MOSFET
VSD	Diode Forward Voltage			1.4	V	IS=3.5A,VGS=0V
trr	Reverse Recovery Time		575		nS	VGS=0V
Qrr	Reverse Recovery Charge		1.9		μC	IS=7A,di/dt=100A /µs

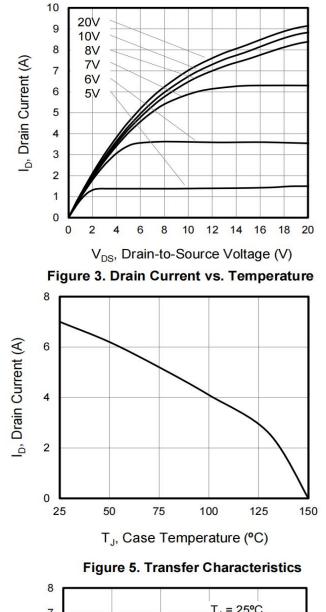
Notes:

- * 1. Repetitive rating, pulse width limited by maximum junction temperature.
- * 2. Pulse Test: Pulse width \leq 300µs, Duty Cycle \leq 1%



Typical Feature Curve





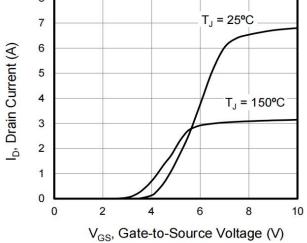
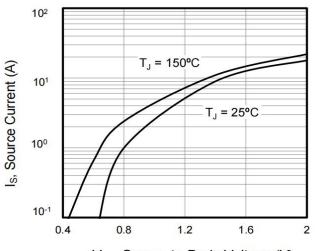


Figure 2. Body Diode Forward Voltage



V_{SD}, Source-to-Drain Voltage (V)

Figure 4. BV_{DSS} Variation vs. Temperature

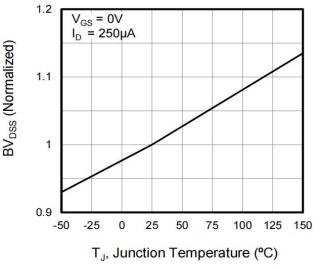
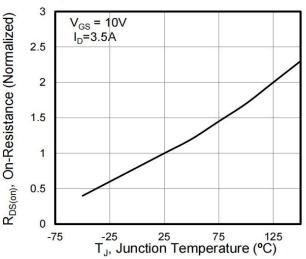


Figure 6. On-Resistance vs. Temperature





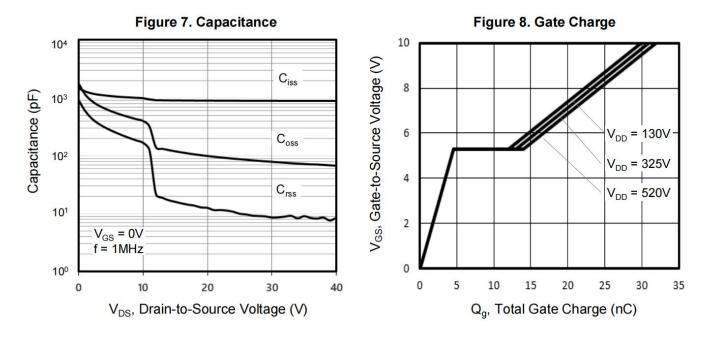
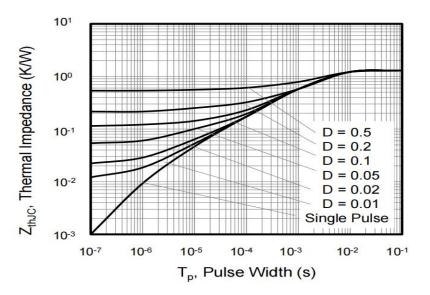


Figure 9. Transient Thermal Impedance





Test Circuits and Waveforms

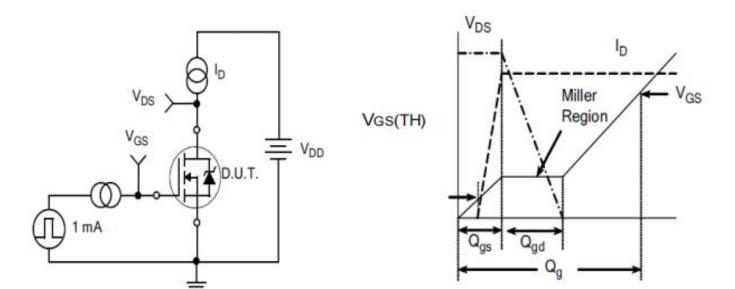
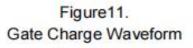


Figure10. Gate Charge Test Circuit



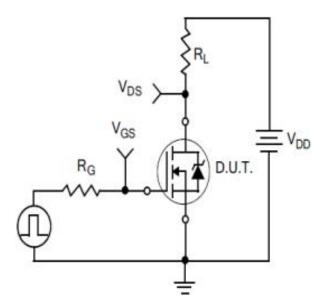


Figure12. Resistive Switching Test Circuit

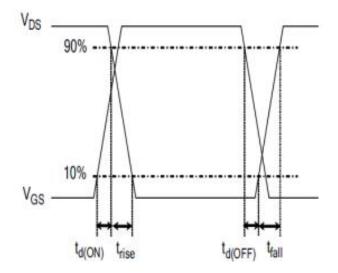
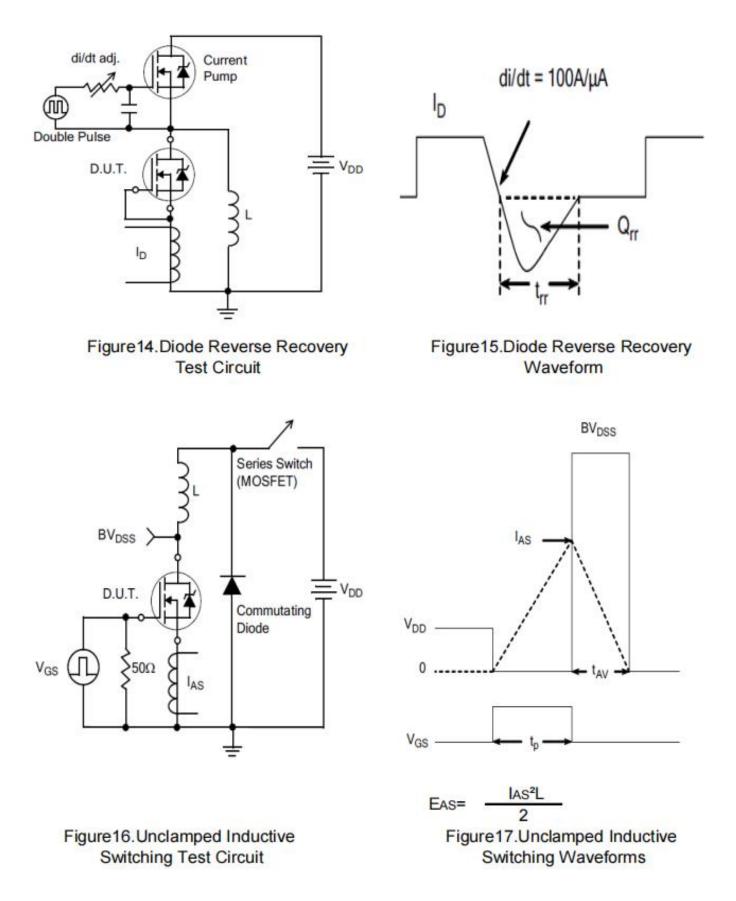


Figure13. Resistive Switching Waveforms

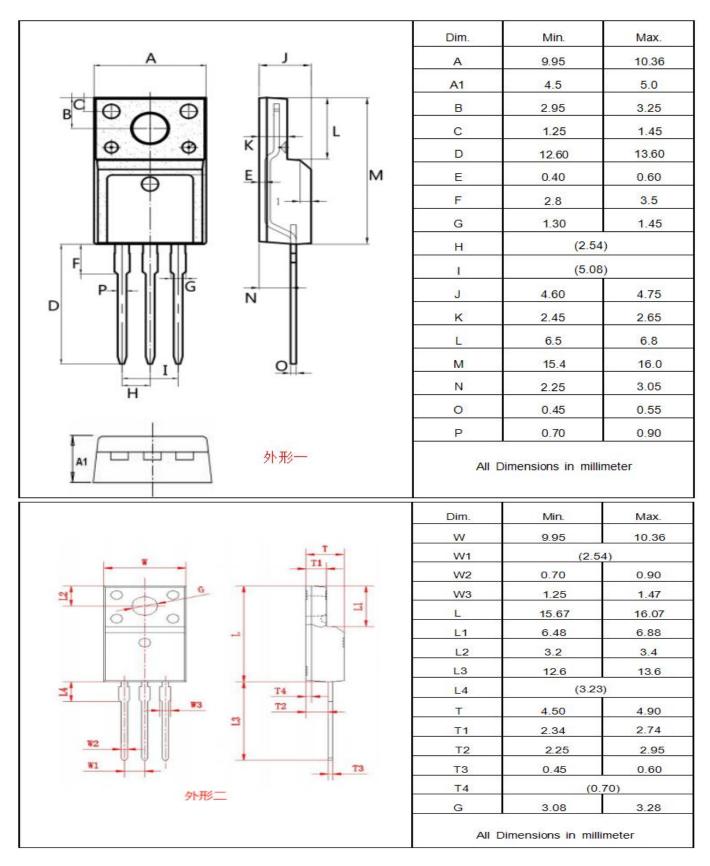


Test Circuits and Waveforms





Package outline drawing(TO-220F Unit: mm)





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